



CPA241



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ABSOLUTE MAXIMUM RATINGS

NOTE:

Refer to parent product data sheet PA241 for typical AC electrical characteristics, precautions, applications and other test parameters.

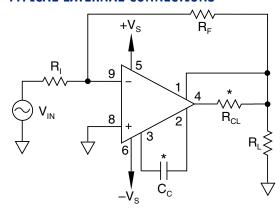
DC WAFER PROBED SPECIFICATIONS

PARAMETER	TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
OFFSET VOLTAGE, initial BIAS CURRENT, initial COMMON MODE REJECTION VOLTAGE SWING SUPPLY CURRENT, quiescent	$V_s = \pm 50V$ $V_{CM} = \pm 90 \text{ V DC}$ $I_O = 40\text{mA}$ $V_S = \pm 50 \text{ V}$	84 ±V _s -12 1.8	15 56 94 ±V _s -10 2.1	40 200 2.3	mV pA dB V mA

NOTES: 1. Unless otherwise stated $V_S = \pm 50 \text{ V}$, $T_A = 25^{\circ}\text{C}$, DC input specification \pm value given.

2. Sample tested by wafer to 95%.

TYPICAL EXTERNAL CONNECTIONS



Required component and value if given.
 Optional balance components are recommended values.
 C_c is NPO, rated for full supply voltage –V_s to +V_s.

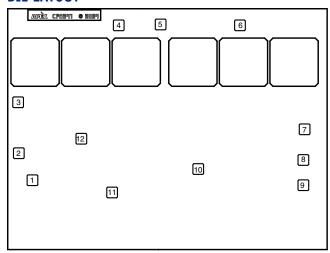
NOTE: Diagram for connection illustration only. All op amp configurations are possible.

Pad	Function	Pad	Function
_1	Output	5	+Vs
2	Compensation	6	-Vs
3	Compensation	8	+IN
4	Current Limit	9	-IN

CAUTION

The CPA241 is a MOSFET amplifier. ESD handling procedures must be observed

DIE LAYOUT



Dimension: $154.5 \times 117.5 \pm 2.5 \text{ Mils.}$

Thickness: 15 Mil (380µ). Backside Metal: None, Silicon. Bond pad: 5 Mil sq (127µ) Al.

Make no connection to bond pads not listed by function.

Note: The backside of the CPA241 die is isolated up to 500V. The top side walls of the CPA241 die are isolated up to 300V.

Ordering Information:

Order #: CPA241DI80:

Die are only available in waffle packages with a total of 80 die per package.